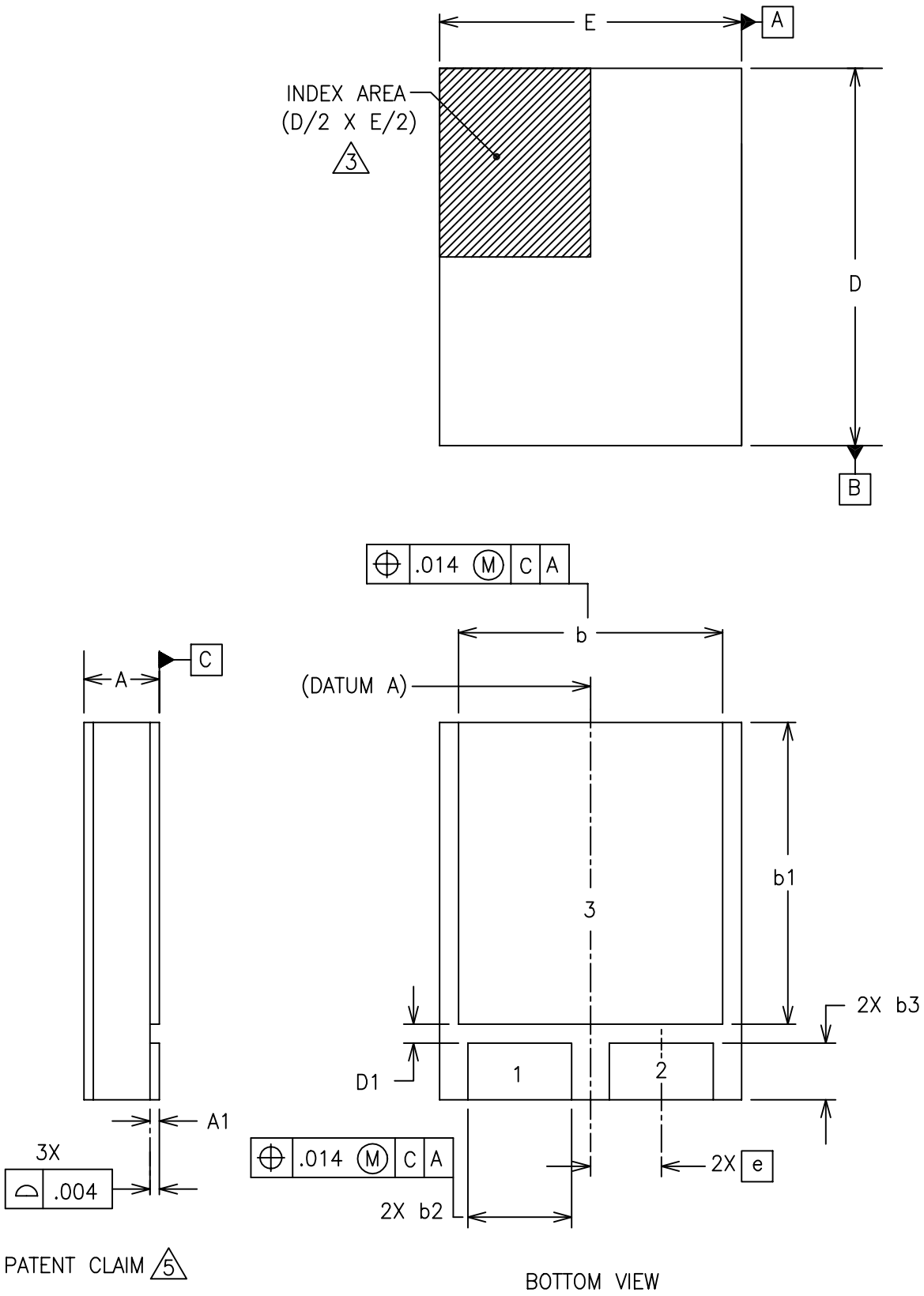

JEDEC SOLID STATE PRODUCT OUTLINE	THIS *REGISTERED OUTLINE* HAS BEEN PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT WITH ANTICIPATED USAGE IN THE ELECTRONICS INDUSTRY; CHANGES ARE LIKELY TO OCCUR.				
TITLE: CERAMIC NO LEAD CHIP CARRIER	PACKAGE DESIGNATOR: R-CBCC-N3	ISSUE: A	DATE: 01/01	TO-276	SHEET: 1 OF 2

VARIATIONS (ALL DIMENSIONS IN INCHES)												
SYMBOL	AA RECTANGULAR			NOTE	AB RECTANGULAR			NOTE	AC RECTANGULAR			NOTE
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.		MIN.	NOM.	MAX.	
A	.112	.118	.124	2	.130	.136	.142	2	.130	.136	.142	2
A1	.010	.015	.020	2	.010	.015	.020	2	.010	.015	.020	2
b	.281	.286	.291	2	.370	.375	.380	2	.435	.440	.445	2
b1	.220	.225	.230	2	.410	.415	.420	2	.470	.475	.480	2
b2	.090	.095	.100	2	.135	.140	.145	2	.135	.140	.145	2
b3	.115	.120	.125	2	.152	.157	.162	2	.152	.157	.162	2
D	.395	.400	.405		.620	.625	.630		.685	.690	.695	
D1	.030	---	---		.030	---	---		.035	---	---	
E	.291	.296	.301		.445	.450	.455		.520	.525	.530	
e	.075 BSC				.105 BSC				.120 BSC			
Note	1, 3, 4, 5				1, 3, 4, 5				1, 3, 4, 5			
Ref.	10-408				10-408				10-408			
Issue	A				A				A			

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. SOLDER FINISH IS OPTIONAL. DIMENSIONS A, A1, b1, b2 AND b3 APPLIES TO A METALLIZED TERMINAL.
3. THE TERMINAL #1 IDENTIFIER MUST BE LOCATED WITHIN THE ZONE INDICATED. DETAILS OF TERMINAL #1 INDENTIFIER ARE OPTIONAL.
4. ALL DIMENSIONS ARE IN INCHES.
5. IT HAS BEEN STATED THAT U.S. PATENT NO. 5,111,277 (HELD BY OLIN AEGIS) MAY RELATE TO CERTAIN APPLICATIONS OF THIS PACKAGE OUTLINE.